

Dell™ Studio XPS™ 8100: Comprehensive Specifications

This document provides information that you may need when setting up, updating drivers for, and upgrading your computer.



NOTE: Offerings may vary by region. For more information regarding the configuration of your computer, click **Start** P Help and Support and select the option to view information about your computer.

Processor		
Туре	Intel [®] Core [™] i7-870	
	Intel Core i7-860	
	Intel Core i7-750	
	Intel Core i5-670	
	Intel Core i5-661	
	Intel Core i5-660	
	Intel Core i5-650	
	Intel Core i3-540	
	Intel Core i3-530	
Ll cache	32 KB	
L2 cache	256 KB/core	

Processor (continued)			
L3 cache			
Intel Core i5-670	upto 4 MB		
Intel Core i5-661			
Intel Core i5-660			
Intel Core i5-650			
Intel Core i3-540			
Intel Core i3-530			
Intel Core i7-750	upto 6 MB		
Intel Core i7-870	upto 8 MB		
Intel Core i7-860			
Memory			
Connectors	four internally-accessible DDR3 DIMM sockets		
Capacities	1 GB, 2 GB, and 4 GB		
Memory type	1066-MHz or 1333-MHz DDR3 DIMM; non-ECC memory only		
Memory configurations possible	4 GB, 6 GB, 8 GB, 12 GB, and 16 GB (64-bit operating system)		
Computer Information			
System chipset	Intel H57		
Data bus width	2.5 GT/s		
DRAM bus width	64 bits		
Processor address bus width	64 bits		
RAID support (internal SATA drives	RAID 0 (striping)		
only)	RAID 1 (mirroring)		
BIOS chip (NVRAM)	8 MB		
Memory speed	1333 Mhz		
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Drives and Devices			
Externally accessible	 two 5.25-inch bays for SATA DVD+/-RW Super Multi Drive or Blu-ray Disc™ combo or Blu-ray Disc RW drive 		
Internally accessible	two 3.5-inch bays for SATA hard drives		
Wireless (optional)	WiFi/Bluetooth® wireless technology		
Expansion Bus			
PCI Express	• Gen2 x1 slot bi-directional speed — 500 MB/s		
	 Gen2 x16 slot bi-directional speed — 16 GB/s 		
PCI	32-bit speed — 33 MHz		
SATA 2.0	1.5 Gbps and 3.0 Gbps		
USB 2.0	• high speed — 480 Mbps		
	• full speed — 12 Mbps		
	• low speed — 1.2 Mbps		

Memory Card Reader			
Cards supported	• CompactFlash (CF) card		
	• Smart Media (SM) card		
	• xD-Picture (xD) card		
	 Memory Stick (MS) card 		
	 Memory Stick Duo card 		
	 Memory Stick PRO Duo card 		
	• Memory Stick PRO (MSPRO) card		
	 Memory Stick PRO HG (MSPRO HG) card 		
	 SecureDigital (SD) card 		
	 SecureDigital Card (SDHC) 2.0 		
	• MultiMedia Card (MMC)		
	• MicroDrive (MD)		
Video			
Integrated	Intel [®] Graphics Media Accelerator HD		
Discrete	PCI Express x16 card		
Audio			
Туре	Integrated 7.1 channel, High Definition audio with S/PDIF support		
System Board Connectors			
Memory	four 240-pin connectors		
PCI	one 124-pin connector		
PCI Express x1	two 36-pin connectors		
PCI Express x16	one 164-pin connector		
Power (system board)	one 24-pin EPS 12V connector		
,	(ATX-compatible)		
Processor fan	one 4-pin connector		

System Board Connectors (continued)			
Chassis fan	one 3-pin connector		
Front USB connector	five 9-pin connectors		
Front audio connector	one 9-pin connector for 2-channel stered sound and microphone		
SATA	four 7-pin connectors		
S/PDIF out	one 5-pin connector		
External Connectors			
Network adapter	RJ45 connector		
USB	two top-panel, two front-panel, and four back-panel USB 2.0-compliant connectors		
Audio	top panel — one headphone and one microphone connector		
	back panel — six connectors for 7.1 support		
S/PDIF	one S/PDIF (optical) connector		
eSATA	one back-panel connector		
IEEE 1394a	one back-panel 6-pin serial connector		
HDMI	19-pin connector		
DVI	24-pin connector		
Expansion Slots			
PCI			
Connectors	one		
Connector size	124-pin connector		
Connector data width (maximum)	32 bit		
PCI Express x1			
Connectors	two		

36-pin connector

Connector size

Expansion	Slots	(continued)
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Connector data width (maximum) 1 PCI Express lane

PCI Express x16

Connectors one

Connector size 164-pin connector

Connector data width (maximum) 16 PCI Express lane

Power

DC Power Supply

Wattage 350 W

Maximum heat dissipation 1836 BTU/hr

NOTE: Heat dissipation is calculated by using the power supply wattage rating.

Input voltage 115/230 VAC

Input frequency 50/60 Hz

Rated output current 8 A/4 A

Battery

Coin-cell battery 3-V CR2032 lithium coin cell

Physical

Height 407.75 mm (16.02 inches)

Width 185.81 mm (7.31 inches)

Depth 454.67 mm (17.90 inches)

Weight 10.18 kg (22.40 lb)

Computer Environment

Temperature range:

Operating 10°C to 35°C (50°F to 95°F)

Storage -40°C to 65°C (-40°F to 149°F)

Relative humidity 20% to 80% (non-condensing)

Computer Environment (continued)

Maximum vibration (using a random-vibration spectrum that simulates user environment):

Operating 0.25 GRMS Storage 2.2 GRMS

Maximum shock (measured with hard drive in head-parked position and a 2-ms half-sine pulse):

Operating Half-Sine Pulse: 40G for 2 ms with a

change in velocity of 20 in/s (51 cm/s)

Storage Half-Sine Pulse: 50G for 26 ms with a

change in velocity of 320 in/s (813 cm/s)

Altitude (maximum):

Operating -15.2 to 3048 m (-50 to 10,000 ft)
Storage -15.2 to 10,668 m (-50 to 35,000 ft)

Airborne contaminant level G2 or lower as defined by ISA-S71.04-

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